

# **WSP08N10**

**N-Ch MOSFET** 

#### **General Description**

The WSP08N10 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSF08N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

# **Product Summery**

| BVDSS | RDSON | ID   |
|-------|-------|------|
| 100V  | 39mΩ  | 7.0A |

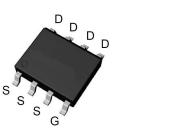
#### Applications

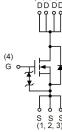
• Power Management in DC/DC Converter.

# **SOP-8** Pin Configuration

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available





## **Absolute Maximum Ratings**

| Symbol                              | Parameter  | Rating     | Units |
|-------------------------------------|--|------------|-------|
| V <sub>DS</sub>                     | Drain-Source Voltage   | 100        | V     |
| V <sub>GS</sub>                     | Gate-Source Voltage  | ±20        | V     |
| I₀@T₀=25℃                           | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 7.0        | А     |
| I <sub>D</sub> @T <sub>C</sub> =70℃ | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> | 5.5        | А     |
| I <sub>DM</sub>                     | Pulsed Drain Current <sup>2</sup>                            | 28         | А     |
| EAS                                 | Single Pulse Avalanche Energy <sup>3</sup>                   | 60         | mJ    |
| I <sub>AS</sub>                     | Avalanche Current  | 9          | А     |
| P₀@T <sub>A</sub> =25℃              | Total Power Dissipation <sup>4</sup>                         | 2.5        | W     |
| T <sub>STG</sub>                    | Storage Temperature Range                                    | -55 to 150 | °C    |
| TJ                                  | Operating Junction Temperature Range                         | -55 to 150 | °C    |

#### **Thermal Data**

| Symbol           | Parameter  | Тур. | Max. | Unit |
|------------------|--|------|------|------|
| R <sub>eja</sub> | Thermal Resistance Junction-ambient <sup>1</sup> |      | 50   | °C/W |
| R <sub>θJC</sub> | Thermal Resistance Junction-Case <sup>1</sup>    |      | 24   | °C/W |



**N-Ch MOSFET** 

## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

| Symbol                               | Parameter                                      | Conditions  | Min. | Тур.  | Max. | Unit |
|--------------------------------------|--|---|------|-------|------|------|
| BV <sub>DSS</sub>                    | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V , I <sub>D</sub> =250uA   | 100  |       |      | V    |
| $\triangle BV_{DSS} / \triangle T_J$ | BVDSS Temperature Coefficient                  | Reference to 25 $^\circ\!\mathrm{C}$ , I_D=1mA  |      | 0.098 |      | V/℃  |
| Б                                    | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =10V , I <sub>D</sub> =7A   |      | 39    | 51   |      |
| R <sub>DS(ON)</sub>                  |  | V <sub>GS</sub> =4.5V , I <sub>D</sub> =4A  |      | 44    | 57   | mΩ   |
| V <sub>GS(th)</sub>                  | Gate Threshold Voltage                         |   | 2.0  | 3.0   | 4.0  | V    |
| $	riangle V_{GS(th)}$                | V <sub>GS(th)</sub> Temperature Coefficient    | $V_{GS} - V_{DS}$ , $I_D - 2500A$   |      | -5.52 |      | mV/℃ |
|                                      | Drain Source Lookage Current                   | $V_{\text{DS}}\text{=}80\text{V}$ , $V_{\text{GS}}\text{=}0\text{V}$ , $T_{\text{J}}\text{=}25^\circ\!\mathrm{C}$ |      |       | 10   |      |
| I <sub>DSS</sub>                     | Drain-Source Leakage Current                   | $V_{\text{DS}}\text{=}80\text{V}$ , $V_{\text{GS}}\text{=}0\text{V}$ , $T_{\text{J}}\text{=}55^\circ\!\mathrm{C}$ |      |       | 100  | uA   |
| I <sub>GSS</sub>                     | Gate-Source Leakage Current                    | $V_{GS}$ = $\pm20V$ , $V_{DS}$ = $0V$   |      |       | ±100 | nA   |
| Rg                                   | Gate Resistance                                | V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz  |      | 1.6   | 3.2  | Ω    |
| Qg                                   | Total Gate Charge (10V)                        |   |      | 40    |      |      |
| Q <sub>gs</sub>                      | Gate-Source Charge                             | V <sub>DS</sub> =80V , V <sub>GS</sub> =10V , I <sub>D</sub> =7A  |      | 6     |      | nC   |
| Q <sub>gd</sub>                      | Gate-Drain Charge                              |   |      | 7     |      |      |
| T <sub>d(on)</sub>                   | Turn-On Delay Time                             |   |      | 11    | 20   |      |
| Tr                                   | Rise Time                                      | $V_{DD}$ =30V , $V_{GEN}$ =10V , $R_{G}$ =6 $\Omega$  |      | 9     | 17   |      |
| T <sub>d(off)</sub>                  | Turn-Off Delay Time                            | I <sub>D</sub> =1A ,RL=30Ω  |      | 60    | 113  | ns   |
| T <sub>f</sub>                       | Fall Time                                      |   |      | 30    | 56   |      |
| Ciss                                 | Input Capacitance                              | V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , f=1MHz   |      | 1600  |      |      |
| C <sub>oss</sub>                     | Output Capacitance                             |   |      | 120   |      | pF   |
| C <sub>rss</sub>                     | Reverse Transfer Capacitance                   |   |      | 75    |      | ]    |

## **Guaranteed Avalanche Characteristics**

| Symbol | Parameter                          | Conditions   | Min. | Тур. | Max. | Unit |
|--------|------------------------------------|--|------|------|------|------|
| EAS    | Single Pulse Avalanche Energy $^5$ | V <sub>DD</sub> =25V , L=0.3mH , I <sub>AS</sub> =9A | 50   |      |      | mJ   |

#### **Diode Characteristics**

| Symbol          | Parameter                                | Conditions   | Min. | Тур. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| I <sub>S</sub>  | Continuous Source Current <sup>1,6</sup> | $V_G = V_D = 0V$ , Force Current                               |      |      | 6    | А    |
| I <sub>SM</sub> | Pulsed Source Current <sup>2,6</sup>     |  |      |      | 28   | А    |
| V <sub>SD</sub> | Diode Forward Voltage <sup>2</sup>       | V <sub>GS</sub> =0V , I <sub>S</sub> =6A , T <sub>J</sub> =25℃ |      |      | 1.1  | V    |
| t <sub>rr</sub> | Reverse Recovery Time                    | IF=7A, dI/dt=100A/µs,Tյ=25℃                                    |      | 61   |      | nS   |
| Q <sub>rr</sub> | Reverse Recovery Charge                  |  |      | 127  |      | nC   |

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

3. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}\text{=}25\text{V}, V_{\text{GS}}\text{=}10\text{V}, \text{L}\text{=}0.3\text{mH}, \text{I}_{\text{AS}}\text{=}9\text{A}$ 

4.The power dissipation is limited by 150  $^\circ\!\!\mathbb{C}$  junction temperature

5. The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



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# **Typical Characteristics**

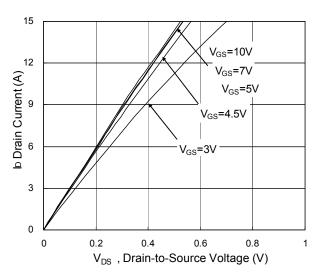


Fig.1 Typical Output Characteristics

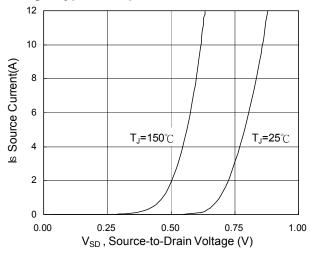


Fig.3 Forward Characteristics Of Reverse

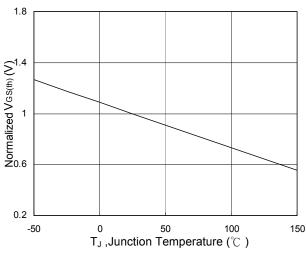


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

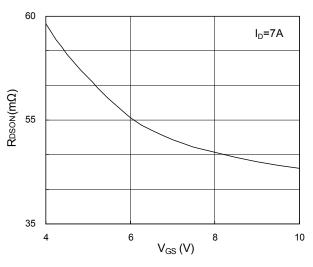


Fig.2 On-Resistance vs. Gate-Source

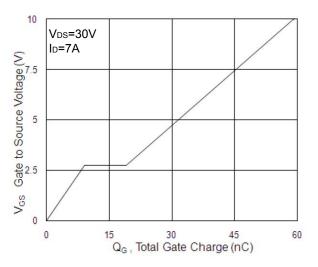


Fig.4 Gate-Charge Characteristics

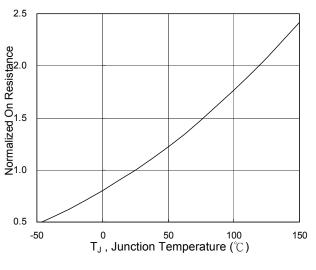


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>

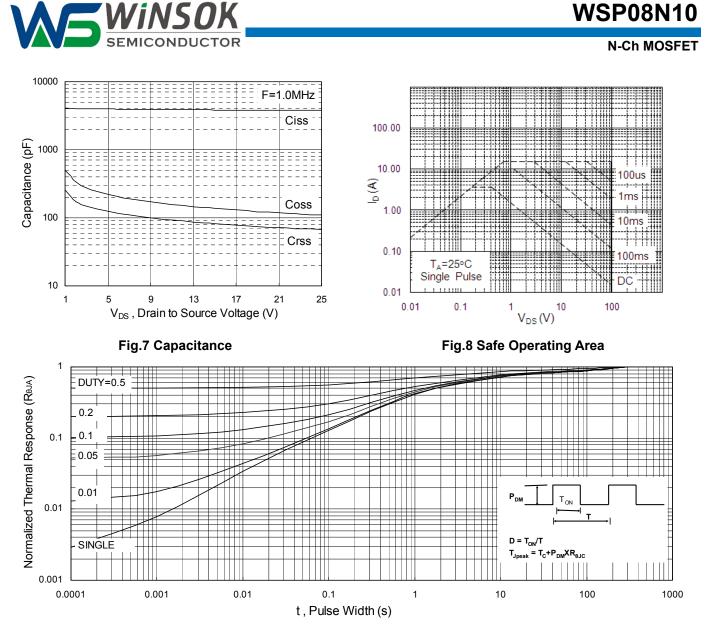
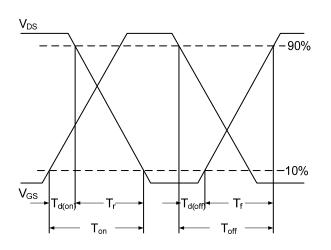
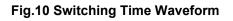


Fig.9 Normalized Maximum Transient Thermal Impedance





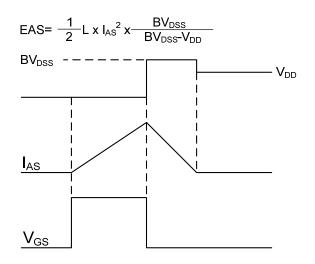


Fig.11 Unclamped Inductive Switching Waveform



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